









Release Date: 18 October 2023 Version: A1.1

PRODUCT DATASHEET



- ► Chip Side View with IC
- ► 1204SV (3210) IC 1.5t
- ► Sky White/Red/Green /Blue

NOM61S43ICSV



1204SV IC-LED





FEATURES (White/Red/Green/Blue*):

- Package: CHIP Side View Package with Integrated IC
- **Forward Current:** 12/12/12/12mA*
- Forward Voltage (typ.): +3.3~+5.5V
- Luminous Intensity (typ.): 270/270/500/90mcd
- Colour: Sky White/Red/Green/Blue
- CCT/Dominant Wavelength (typ.): 9900K/622/525/470nm
- Viewing Angle: 120°
- **Materials:**
 - Resin: Epoxy (White Diffused)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- IC Features: This IC LED product is much smaller than PLCC type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Pixel: Each RGBW chip is 8 bit control, total of 4294M colour can be displayed.
- Soldering Methods: IR Reflow soldering
- MSL Level: acc. to JEDEC Level 3
- Packing: 8mm tape with max.3000pcs/reel, ø180mm (7")

* in order of White/White/Red/Green/Blue

1204SC IC-Integrated

- **APPLICATIONS:** Telecommunication
- Indicator
- Home Appliance
- **Decoration Lighting**
- Full Colour LED Strip
- **Gaming Device**
- **Guardrail Tube**



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
LED Output Current	Іоит	25	mA
Supply Voltage	V _{DD}	6	V
Power Dissipation	P _D	400	mW
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

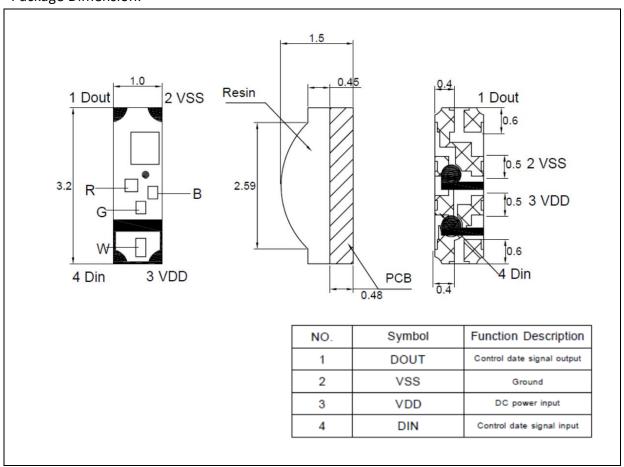
Electrical & Optical Characteristics (Ta=25°C, V_{DD}=5V)

Parameter	Symbol		Values	Unit	Test		
T di diffictei		Зуппоот	Min.	Тур.	Max.	Offic	Condition
Forward Voltage		V _F	3.3	5.0	5.5	V	
Each R/G/B Current		I _{OL}		12		mA	V _{DD} =5V
Input High Voltage		ViH	2.7		V_{DD}	V	DI
Input Low Voltage		VIL	0		1.0	V	DI
Output High Voltage	Output High Voltage					V	I _{OH} =4mA
Output Low Voltage	Output Low Voltage				0.4 V _{DD}	V	I _{OL} =4mA
Operation Current	Operation Current				2	mA	B, G, R no load
Pull Down Resistance	Pull Down Resistance			500K		Ω	D _{IN} , D _{OUT} (VDD=5V)
	R			270			
Luminous Intensity	G	lv		500		mcd	V _{DD} =5V
Luminous intensity	В	IV		90		mca	VDD=3V
	W			270			
	R			622			
Dominant Wavelength	G	λ_{D}		525		nm	V _{DD} =5V
	В			467			
Viewing Angle		2θ _{1/2}		120		deg	I _F =12mA



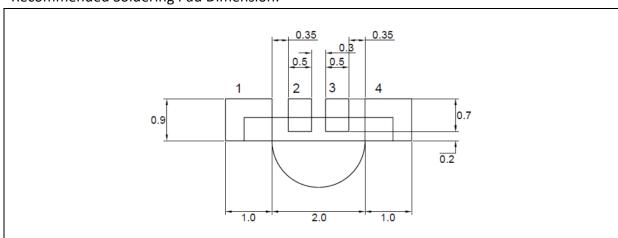
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

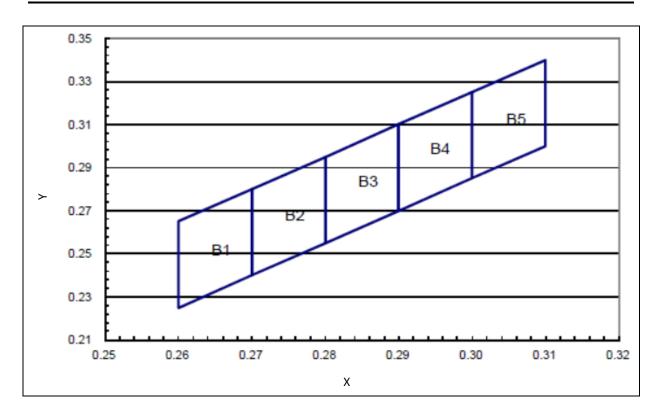
Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



CIE CHROMATICITY DIAGRAM:

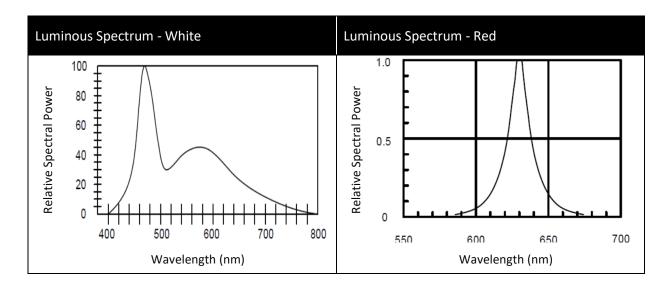


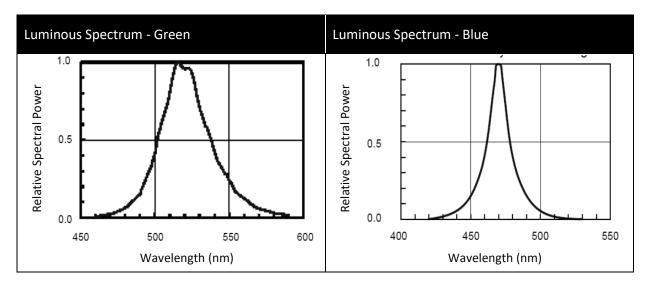
Chromaticity Coordinates Classifications:

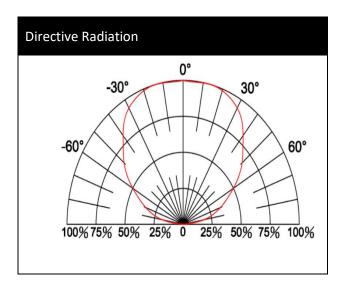
	1	1	-	2	5	3	4			
	Х	Υ	Х	Υ	Х	Υ	Х	Υ		
B1	0.2600	0.2650	0.2600	0.2250	0.2700	0.2400	0.2700	0.2800		
B2	0.2700	0.2800	0.2700	0.2400	0.2800	0.2550	0.2800	0.2950		
В3	0.2800	0.2950	0.2800	0.2550	0.2900	0.2700	0.2900	0.3100		
B4	0.2900	0.3100	0.2900	0.2700	0.3000	0.2850	0.3000	0.3250		
B5	0.3000	0.3250	0.3000	0.2850	0.3100	0.3000	0.3100	0.3400		



ELECTRO-OPTICAL CHARACTERISTICS:



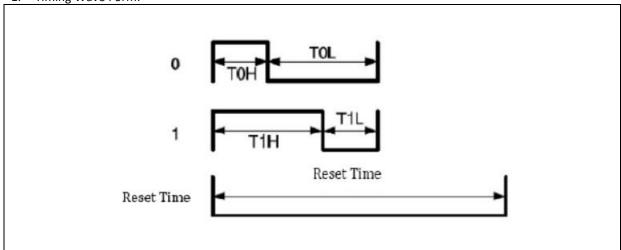






Function Description:

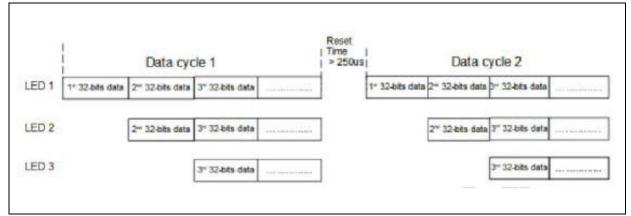
1. Timing Wave Form:



2. High Speed Mode:

Item	Description	min	Typical	Allowance	unit
ТОН	0 code, High-level time		0.3	±0.15	us
TOL	0 code, Low-level time		0.9	±0.15	us
T1H	1 code, High-level time		0.9	±0.15	us
T1L	1 code, Low-level time		0.3	±0.15	us
Trst	Reset code,Low-level time	250			

3. Data Communication:





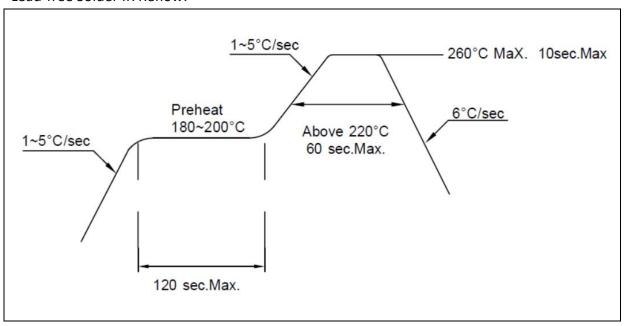
4. Single Data in 32bit for RGBW:

M	SE	3																											LS	В	_
R	R	R	R	R	R	R	R	G	G	G	G	G	G	G	G	В	В	В	В	В	В	В	В	W	W	W	W	w	w	w	W



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder IR Reflow:



Note:

- 1. We recommend the reflow temperature 240°C (± 5 °C). The maximum soldering temperature should be limited to 260°C.
- 2. Maxima reflow soldering: 1 time.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 168 hours. Otherwise, they should be kept in a damp-proof box with descanting agent stored at R.H.<10% and apply baking before use.

Over-Current Proof:

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burnout will happen.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	15/11/2021	Datasheet set-up.
A1.1	18/10/2023	Update IC Functions.